Docket No.

202450US0

IN RE APPLICATION OF:

Atsushi SHIOTA, et al.

SERIAL NO:

09 770,289

FILED:

January 29, 2001

PROCESS FOR PRODUCING SILICA-BASED FILM, SILICA-BASED FILM, INSULATING FILM, AND

FOR:

SEMICONDUCTOR DEVICE

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

## SIR:

Transmitted herewith is an Amendment w Marked Up Copy (7) in the above-identified application.

- No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☐ Additional documents filed herewith:



The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS		RATE	+	CALCULATIONS
TOTAL	16	MINUS	20	0	×	\$18	=	\$0.00
INDEPENDENT	1	MINUS	1	0	×	\$84	=	\$0.00
		☐ MULTIPLE DEPENDENT CLAIMS			-	\$280	=	\$0.00
		TOTAL OF ABOVE CALCULATIONS					NS	\$0.00
☐ Reduction by 50% for filing by Small Entity							\$0.00	
		☐ Recordation of Assignment			+	\$40	=	\$0.00
					•	TOTA	4L	\$0.00

 $\square$  A check in the amount of \$0.00 is attached.

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Certha Vant Clark 1994

Norman F. Oblon

Registration No. 24,618

Corwin P. Umbach, Ph.D.

22850

Customer Number 22850 Tel. (703) 413-3000 Tel. (703) 22256 202450US0

## IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

ATSUSHI SHIOTA ET AL. : GROUP ART UNIT: 1712

SERIAL NO: 09/770,289

FILED: JANUARY 29, 2001 : EXAMINER: FEELY, M.

FOR: PROCESS FOR PRODUCING SILICA-BASED FILM, SILICA-BASED FILM, INSULATING FILM,

**AMENDMENT** 

RECEIVED

MAY 24 2692

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

AND SEMICONDUCTOR DEVICE

TC 1700

SIR:

In response to the Office Action dated February 28, 2002, please amend the application identified above as follows (marked-up copy of amendments attached):

## IN THE CLAIMS

Please amend Claims 1, 3 and 6 as follows:

1. (Amended) A process for producing a silica-based film, the process comprising irradiating a film comprising at least one siloxane compound with electron beams at an irradiation dose of from 1 to 500  $\mu$ C cm<sup>2</sup> to thereby convert the film into a film having a dielectric constant of 3 or lower and having silicon carbide bonds represented by Si-C-Si.